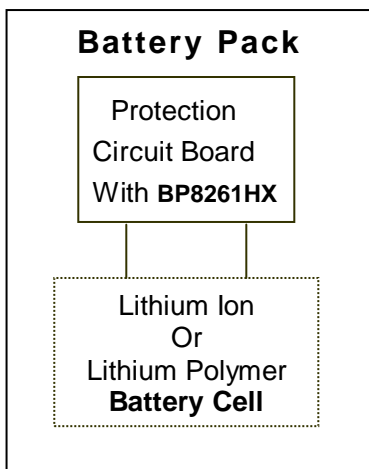


General Description

The BP8261HX is protector for lithium-ion and lithium polymer rechargeable battery with high accuracy voltage detection. It can be used for protecting single cell packs from overcharge, overdischarge, over current and short circuit. The IC has suitable protection delay functions and low power consumption property.

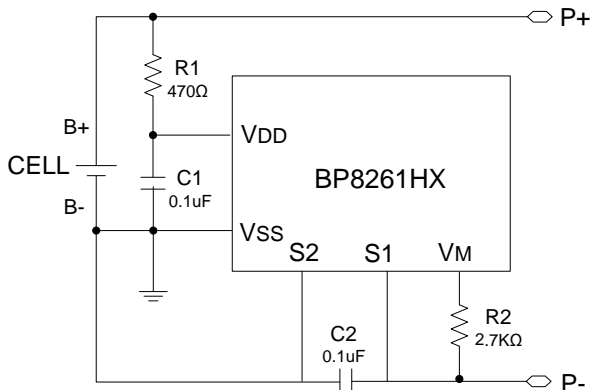
Applications



Features

- **Overcharge Detection Voltage**
 - 4.425V
 - Accuracy ±50mV (Ta=25°C)
- **Overdischarge Detection Voltage**
 - 2.470V
 - Accuracy ±100mV (Ta=25°C)
- **Discharge Overcurrent Detection Voltage**
 - 0.150V (V_{DD} = 3.300V)
 - Accuracy ±30mV (Ta=25°C)
- **Short Circuit Detection Voltage**
 - Typ. 0.9V (V_{DD} = 3.300V)
 - Accuracy ±300mV (Ta=25°C)
- **Low Current Consumption**
 - Standard working current
Typ. 3.0uA (V_{DD} = 3.500V, Ta=25°C)
 - With auto wake up
Typ. 0.5uA (V_{DD} = 1.8V, Ta=25°C)
- **Auto Wake up function is allowed**
- **0V charge function is allowed**
- **Small Package**
 - DFN2.2*2.9-6LT
- **FET general characteristics**
 - V_{DS}=20V
 - R_{SS(ON)}<40 mΩ (V_{GS}=3.7V, I_D=1A)
 - ESD Rating: 2000V HBM

Typical Application Circuits



R₁ and C₁ are to stabilize the supply voltage of the BP8261HX. R₁ C₁ is hence regarded as the time constant for V_{DD} pin. R₁ and R₂ can also be a part of current limit circuit for the BP8261HX.

Recommended values of these elements are as follows:

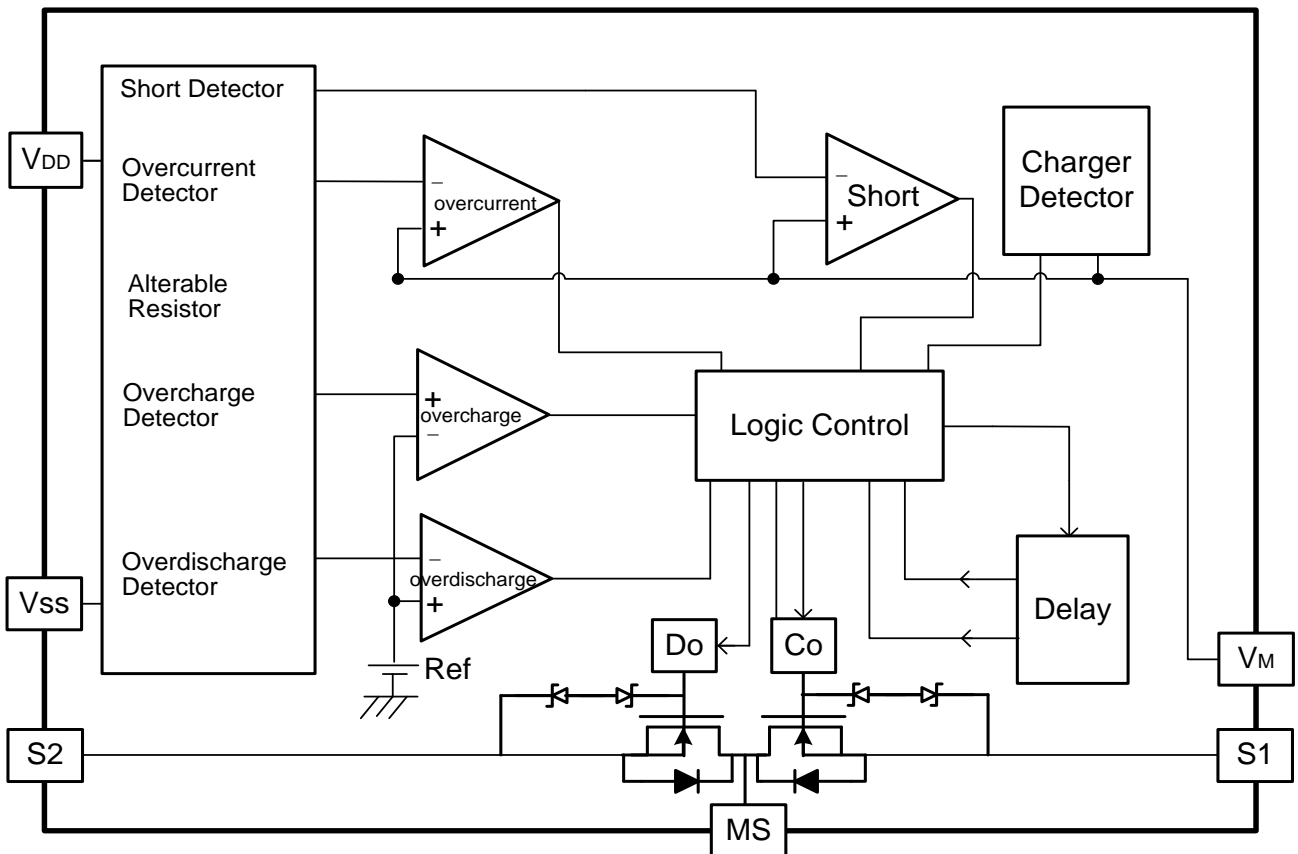
- R₁ < 1KΩ. A larger value of R₁ results in higher detection voltage, introducing errors.
- 1.5KΩ < R₂ < 4KΩ. A larger value of R₂ possibly prevents resetting from Overdischarge even with a charger.
- R₁+ R₂ > 1.6KΩ. Smaller values may lead to power consumption over the maximum dissipation rating of the BP8261HX.

The requirement or resistors and capacitors and the value of constants should be decided depending upon the system function and characteristics.

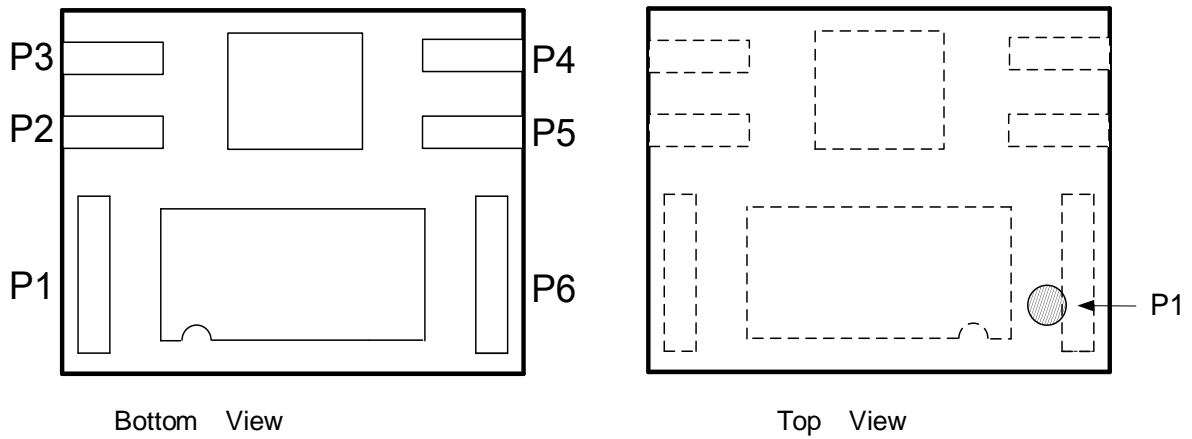
Marking Contents

| Part number | Marking | Package | Quantity per reel |
|-------------|---------|------------------|-------------------|
| BP8261HX | VBEB | DFN2.2*2.9 - 6LT | 3000 |

Block Diagram



Pin Description



| Pin | Symbol | Description |
|-----|-----------------|--|
| P1 | S2 | The source terminal of MOSFET switch for discharge control |
| P2 | V _{SS} | Ground |
| P3 | V _{DD} | Power supply |
| P4 | NC | No Connection |
| P5 | V _M | Connected to charger's negative pin |
| P6 | S1 | The source terminal of MOSFET switch for charge control |
| P7 | IS | The substrate of IC, IS should be floating |
| P8 | MS | The common drain terminal of MOS, MS should be floating |

Electrical Characteristics

 (T_{OPT}=25°C unless otherwise specified)

| Symbol | Item | Conditions | Min. | TYP. | Max. | Unit |
|---|---|---|-------|-----------------------|-------|------|
| DETECTION VOLTAGE AND DELAY TIME | | | | | | |
| Vdet1 | Overcharge Detection Voltage | | 4.375 | 4.425 | 4.475 | V |
| Vrel1 | Release Voltage For Overcharge Detection | | 4.155 | 4.225 | 4.295 | V |
| Vdet2 | Overdischarge Detection Voltage | | 2.370 | 2.470 | 2.570 | V |
| Vrel2 | Release Voltage For Overdischarge | | 2.950 | 3.100 | 3.250 | V |
| Vdet3 | Discharge Overcurrent Detection Voltage | V _{DD} = 3.30V | 0.120 | 0.150 | 0.180 | V |
| Vshort | Short Protection Voltage | V _{DD} = 3.30V | 0.6 | 0.9 | 1.2 | V |
| Tvdet1 | Overcharge Detection Delay Time | V _{DD} = 4.0V→4.5V | 1.02 | 1.28 | 1.54 | s |
| Tvdet2 | Overdischarge Detection Delay Time | V _{DD} = 3.0→2.0V | - | 24 | 100 | ms |
| Tvdet3 | Discharge Overcurrent Detection Delay Time | V _{DD} = 3.30V | - | 12 | 20 | ms |
| Tshort | Short Detection Delay Time | V _{DD} = 3.30V | - | 375 | 550 | us |
| OUTPUT VOLTAGE AND V_M INTERNAL RESISTANCE | | | | | | |
| V _{COL} | CO Pin L Voltage | I _{OL} =50uA, V _{DD} =4.4V | 0.150 | 0.200 | 0.250 | V |
| V _{COH} | CO Pin H Voltage | I _{OH} =-50uA, V _{DD} =3.9V | 3.750 | 3.700 | 3.650 | V |
| V _{DOL} | DO Pin L Voltage | I _{OL} =50uA, V _{DD} =2.0V | 0.050 | 0.070 | 0.090 | V |
| V _{DOH} | DO Pin H Voltage | I _{OH} =-50uA, V _{DD} =3.9V | 3.850 | 3.830 | 3.810 | V |
| R _{VMD} | Resistance between V _M and V _{DD} | V _{DD} =2.0V, V _M =0V | 150 | 300 | 600 | KΩ |
| R _{VMS} | Resistance between V _M and V _{SS} | V _{DD} =3.3V, V _M =1V | 60 | 130 | 260 | KΩ |
| OPERRATION VOLTAGE AND CURRENT CONSUMPTION | | | | | | |
| V _{DD} | Operating Input Voltage | V _{DD} -V _{SS} | 1.6 | V_{DD} | 7.0 | V |
| V _M | Operating Input Voltage | V _{DD} -V _M | 1.5 | - | 18.0 | V |
| I _{DD} | Supply Current | V _{DD} = 3.5V, V _M = 0V | - | 3.0 | 6.0 | uA |
| I _{STANDBY} | Standby Current(with Auto wake up) | V _{DD} =V _M = 1.8V | - | - | 0.5 | uA |

Absolute Maximum Ratings

 (Ta=25°C, V_{SS}=0 V)

| Item | Symbol | Ratings | Unit |
|----------------------------------|------------------|--|------|
| Supply Voltage | V _{DD} | -0.3 to 7 | V |
| V _M Pin Input Voltage | V _M | V _{DD} -18 to V _{DD} +0.3 | V |
| Gate-Source Voltage | V _{GS} | ±10 | V |
| Drain- Source Voltage | V _{DS} | 20 | V |
| Drain Current | I _D | 6 | A |
| Co Pin Output Voltage | V _{CO} | V _{DD} -18 to V _{DD} +0.3 | V |
| Do Pin Output Voltage | V _{DO} | V _{SS} -0.3 to V _{DD} +0.3 | V |
| Power Dissipation | P _d | 150 | mW |
| Operating Temperature Range | T _{opt} | -30 to 80 | °C |
| Storage Temperature Range | T _{stg} | -55 to 125 | °C |

Caution: These values must not be exceeded under any conditions.
Electrical Characteristics

(25 °C, GND=0V unless otherwise specified)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Notes |
|--------------------------------------|----------------------|------|------|------|------|--|
| Drain current at cut off of MOS-FET | I _{DSS} | | | 1 | uA | V _{ds} =20V |
| Source -source on state resistance 1 | R _{SS(on)1} | 21 | 33 | 45 | mΩ | V _{dd} =2.6V , I _D =1.0A |
| Source -source on state resistance 2 | R _{SS(on)2} | 20 | 30 | 40 | mΩ | V _{dd} =3.7V , I _D =1.0A |
| Source -source on state resistance 3 | R _{SS(on)3} | 19 | 29 | 39 | mΩ | V _{dd} =4.2V , I _D =1.0A |
| Body Diode-Forward Voltage | V _{SD} | 0.60 | 0.74 | 1.20 | V | I _s =1.0A , V _{GS} =0V |

Function Description

Normal Condition:

V_{DD} is between the Overdischarge Detection Voltage (V_{det2}) and Overcharge Detection Voltage (V_{det1}) and the V_M voltage is between V_{SS} and the Discharge Overcurrent Detection Voltage (V_{det3}), therefore the MOS-FET of charge and discharge are all on. Charging and discharging can be carried out freely.

Overcharge Condition:

When V_{DD} increases and passes V_{det1} during charging under the normal condition, the charge control FET turns off after Overcharge Detection Delay Time (T_{vdet1}), discharging is stopped. It calls overcharge protection.

Overcharge Protection Release Condition:

The charging state can be reset and charge control FET will turn on, as follow condition:

- (1) When the V_M voltage is between V_{det3} and V_{SS} , V_{DD} becomes lower than the Overcharge Release Voltage (V_{rel1}), the charge control FET turns on.
- (2) When a charger is disconnected with the battery pack and a load is connected, and the V_{DD} level is lower than V_{det1} , the charge control FET turns on.

Note: when a charger keep connecting, even if V_{DD} level is lower than V_{rel1} , the overcharge state will not release and charge control FET keep off until disconnect the charger with the battery pack.

Overdischarge Condition:

While discharging, after V_{DD} lowers below Overdischarge Detection Voltage (V_{det2}), the discharge control FET turns off after Overdischarge Detection Delay Time (T_{vdet2}), discharging is stopped. It calls overdischarge protection.

Overdischarge Protection Release Condition:

When IC is in overdischarge condition, if a charger is connected to the battery pack, and the battery supply voltage becomes higher than V_{det2} , the discharge control FET turns on, allowing discharging action.

The discharging state also can be reset and the output of D_o becomes high when V_{DD} becomes higher than the Overdischarge Release Voltage (V_{rel2}), V_M is between V_{SS} and V_{DD} .

When a charger is connected from the battery pack, while the V_{DD} level is lower than V_{det2} , the battery pack makes charger current allowable through the internal parasitic diode.

Discharge Overcurrent Protection:

During discharging, the current varies with load, and V_M increases with the rise of the discharging current. Once V_M rises up to the Discharge Overcurrent Detection Voltage (V_{det3}) or higher and stays longer than the Discharge Overcurrent Delay Time (T_{vdet3}), IC will turn off the discharge control FET. After that Discharge Overcurrent state is removed, i.e. $V_M < V_{det3}$, and the circuit recovers to normal condition. The current of Discharge Overcurrent protection is related to V_{det3} and the ON resistance of the two FETs ($R_{SS(on)}$).

Short Circuit Protection:

This function has the same principle as the overcurrent protection. But, the Short Circuit Protection Delay Time (T_{short}) is far shorter than T_{vdet3} , and the Short Protection Detection Voltage (V_{short}) is far higher than V_{det3} . When the circuit is shorted, V_M increases rapidly. Once $V_M \geq V_{short}$, IC will turn off the discharge control FET. After the short circuit state is removed, i.e. $V_M < V_{det3}$, the circuit recovers to the normal condition. The short circuit peak current is related to V_{short} and the ON resistance of the two FETs ($R_{SS(on)}$).

0V Battery Charge Function:

This function is used to recharge the connected battery whose voltage is 0V due to the self-discharge. When the 0 V battery charge starting charger voltage (V_{0cha}) or higher is applied between P+ and P- pins (in the Typical Application Circuits of Page1) by connecting a charger, the charge control FET gate is fixed to V_{DD} pin voltage. When the voltage between the gate and source of the charge control FET becomes equal to or higher than the turn-on voltage by the charger voltage, the charge control FET turns on to start charging. At this time, the discharge control FET is off and the charging current flows through the internal parasitic diode in the discharge control FET. When the battery voltage becomes equal to or higher than the Overdischarge Detection Voltage (V_{det2}), the IC enters the normal condition.

Test Circuits

(1) Overcharge detection voltage and overcharge release voltage (Test circuit 1)

The Overcharge Detection Voltage (V_{det1}) is the voltage between V_{DD} and V_{SS} to which when V_1 increases and keeps the condition for overcharge delay time, The charging control FET turns off, V_{S1} is the threshold of a diode, The Overcharge Release Voltage (V_{rel1}) is the voltage between V_{DD} and V_{SS} to which when V_1 decreases, The charging control FET turns on, $V_{S1}=0V$.

(2) Overdischarge detection voltage and Overdischarge release voltage (Test circuit 1)

The Overdischarge Detection Voltage (V_{det2}) is the voltage between V_{DD} and V_{SS} to which when V_1 decreases and keep the condition for overdischarge delay time, The discharging control FET turns off, $V_{S1}=V_1$. The overdischarge Release Voltage (V_{rel2}) is the voltage between V_{DD} and V_{SS} to which when V_1 increases, The discharging control FET turns on, $V_{S1}=0V$.

(3) Discharge overcurrent detection voltage and short circuit detection voltage (Test circuit 2)

The Discharge Overcurrent Detection Voltage (V_{det3}) is the voltage between V_M and V_{SS} to which when V_M increases and keep the condition for Discharge Overcurrent Delay Time (T_{vdet3}), The discharging control FET turns off, $V_{S1}=V_1$.

The Short Circuit Detection Voltage (V_{short}) is the voltage between V_M and V_{SS} to which when V_M increases and keep the condition for Short Circuit Delay Time (T_{short}), The discharging control FET turns off, $V_{S1}=V_1$.

(4) Normal operation current consumption and power down current consumption (Test circuit 2)

Set $V_1=3.9V$ and $V_2=0V$ under normal condition, the current I_{DD} flowing through V_{DD} pin is the normal operation consumption current (I_{DD}).

Set $V_1=3.9V$ and $V_2=0V$, let IC work in normal condition, set V_1 from $3.9V$ to $2.0V$, then let V_M floating under overdischarge condition, the current I_{DD} flowing through V_{DD} pin is the power down current consumption ($I_{STANDBY}$).

(5) Overcharge detection delay time and overdischarge detection delay time (Test circuit 3)

If V_1 increases to be V_{det1} or over V_{det1} and keeps the condition for some time, the charging control FET will turn off, V_{s1} is the threshold of a diode, The time is called overcharge detection delay time. It is used to judge whether overcharge happens indeed.

If V_1 decreases to be V_{det2} or below V_{det2} and keeps the condition for some time, the discharging control FET will turn off, $V_{s1}=V_1$. The time is called overdischarge detection delay time. It is used to judge whether overdischarge happens indeed.

(6) Discharge overcurrent detection delay time and short circuit detection delay time (Test circuit 4)

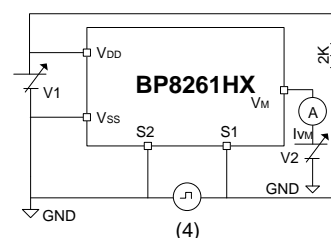
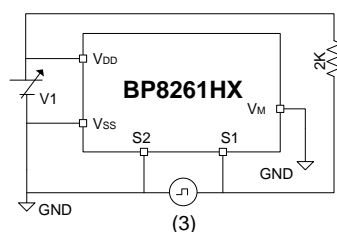
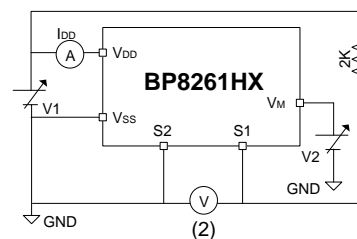
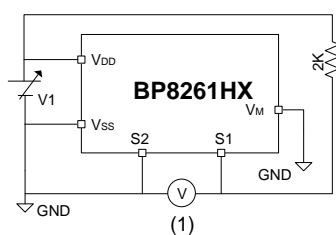
If V_2 increases to be V_{det3} or over V_{det3} and keeps the condition for some time, the discharging control FET will turn off, $V_{s1}=V_1$. The time is called Discharge Overcurrent Delay Time. It is used to judge whether Discharge Overcurrent happens indeed.

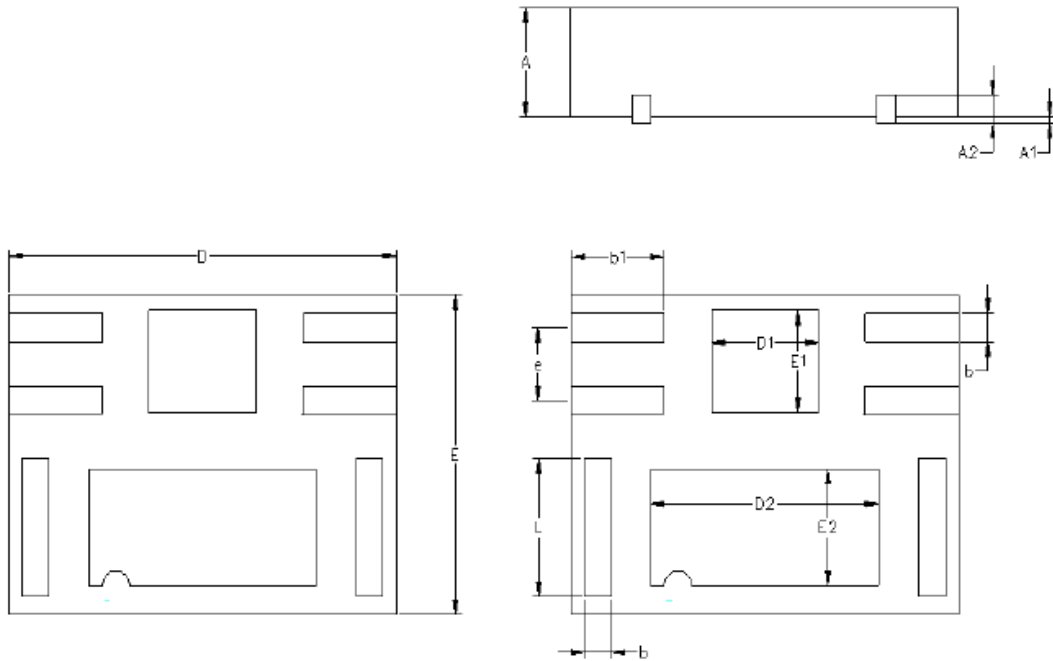
If V_2 increases to be V_{short} or over V_{short} and keeps the condition for some time, the discharging control FET will turn off, $V_{s1}=V_1$. The time is called short circuit delay time. It is used to judge whether short circuit happens indeed.

(7) Internal resistance V_M-V_{DD} and V_M-V_{SS} (Test circuit 4)

Set $V_1=2.0V$, $V_2=0V$, V_1/I_{VM} is the internal resistance R_{VMD} .

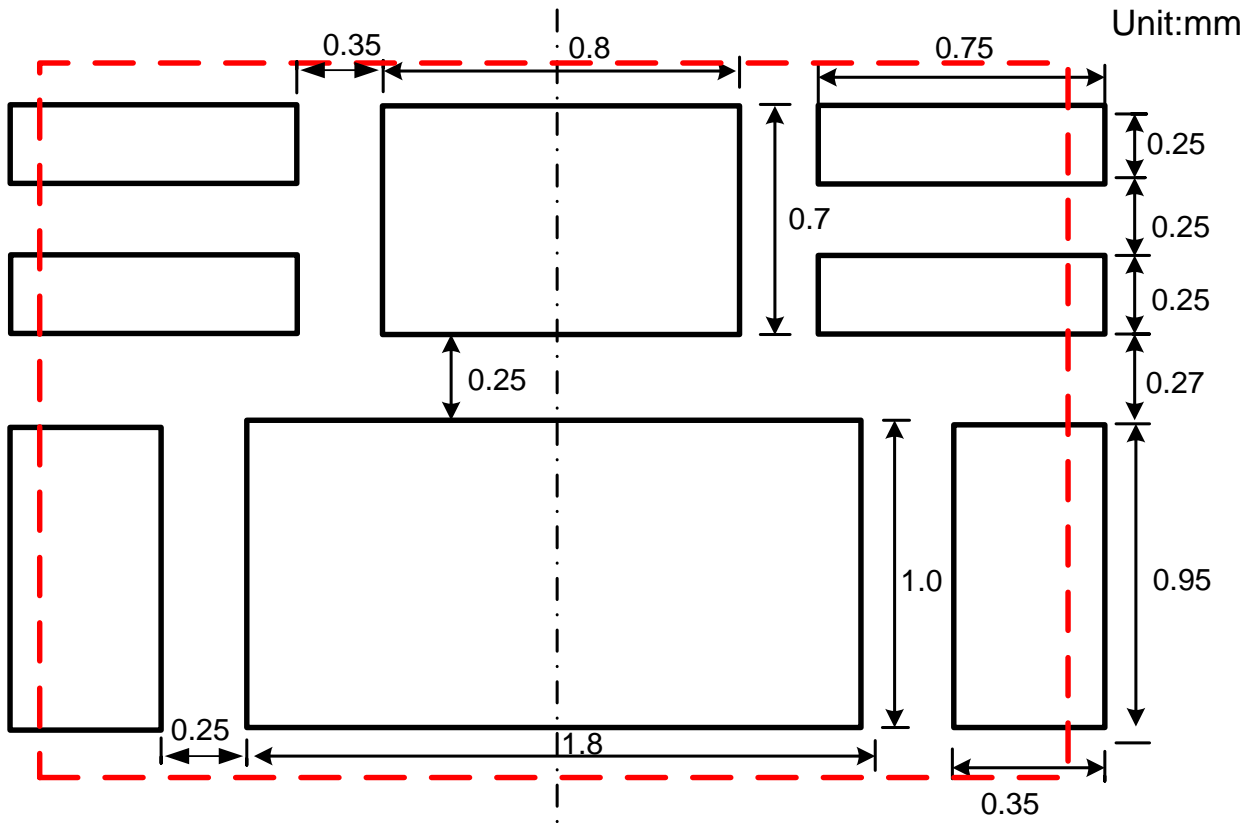
Set $V_1=3.3V$, $V_2=1V$, V_2/I_{VM} is the internal resistance R_{VMS} .



Package Outline
DFN 2.2*2.9-6LT

Dimensions (mm)

| COMMON DEIMENSIONS(mm) | | | |
|------------------------|---------|------|------|
| RER | MIN | NOM | MAX |
| A | 0.45 | 0.50 | 0.55 |
| A1 | 0.00 | | 0.05 |
| A2 | 0.15REF | | |
| D | 2.85 | 2.90 | 2.95 |
| E | 2.15 | 2.20 | 2.25 |
| D1 | 0.75 | 0.80 | 0.85 |
| E1 | 0.65 | 0.70 | 0.75 |
| b | 0.15 | 0.20 | 0.25 |
| e | 0.50BSC | | |
| L | 0.90 | 0.95 | 1.00 |
| b1 | 0.65 | 0.70 | 0.75 |
| D2 | 1.65 | 1.70 | 1.75 |
| E2 | 0.75 | 0.80 | 0.85 |

PCB Layout



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [Battery Management](#) category:

Click to view products by [Shenzhen JingYang](#) manufacturer:

Other Similar products are found below :

[NCP1851BFCCT1G](#) [NCP1855FCCT1G](#) [FAN54063UCX](#) [MP2615GQ-P](#) [LC05132C01NMTTGTG](#) [ISL95522HRZ](#) [BD8665GW-E2](#)
[ISL9538HRTZ](#) [ISL95522AIRZ](#) [S-82D1AAA-A8T2U7](#) [S-8224ABA-I8T1U](#) [MP2615CGQ-P](#) [ISL6251HRZ](#) [ISL6253HRZ](#) [ISL6292-2CR3](#)
[ISL6292BCRZ-T](#) [ISL6299AIRZ](#) [ISL9211AIRU58XZ-T](#) [ISL9214IRZ](#) [ISL9220IRTZ-T](#) [FAN54161UCX](#) [SY6982CQDC](#)
[IP6566_AC_30W_ZM](#) [WS3221C-6/TR](#) [ADBMS1818ASWAZ-RL](#) [ADBMS6815WCSWZ](#) [ML5245-005AMBZ07CX](#) [ADBMS1818ASWZ-](#)
[R7](#) [KA49503A-BB](#) [SC33771CTA1MAE](#) [BQ24060DRCR](#) [BQ7695202PFBR](#) [BQ21080YBGR](#) [BQ771809DPJR](#) [BQ24179YBGR](#)
[BQ7693002DBTR](#) [BQ25170DSGR](#) [TP4586](#) [FM2119L](#) [FM1623A](#) [DW01](#) [BQ25172DSGR](#) [DW01S](#) [TP4054](#) [MP2723GQC-0000-Z](#)
[MP26124GR-Z](#) [MP2664GG-0000-Z](#) [MP26029GTF-0000-Z](#) [MP2695GQ-0000-Z](#) [XB5608AJ](#)